

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00732	4.44	0.12432
	Doped silicon	Silicon (Si)	7440-21-3	0.15771	95.67	2.67876
			<b>Subtotal</b>	<b>0.16503</b>	<b>100.11</b>	<b>2.80308</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.48066	100.0	8.16423
			<b>Subtotal</b>	<b>0.48066</b>	<b>100</b>	<b>8.16423</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02744	5.0	0.466
	Silver alloy	Silver (Ag)	7440-22-4	0.00823	1.5	0.1398
	Lead alloy	Lead (Pb)	7439-92-1	0.51304	93.5	8.7142
			<b>Subtotal</b>	<b>0.54871</b>	<b>100</b>	<b>9.32</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.06488	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01946	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	64.79436	99.87	1100.5674
			<b>Subtotal</b>	<b>64.8787</b>	<b>100</b>	<b>1102</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.13364	100.0	2.27
			<b>Subtotal</b>	<b>0.13364</b>	<b>100</b>	<b>2.27</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.52071	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.37934	10.0	57.4
	Filler	Silica fused	60676-86-0	25.34508	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.37934	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.16897	0.5	2.87
			<b>Subtotal</b>	<b>33.79344</b>	<b>100</b>	<b>574</b>
			<b>Total</b>	<b>100.00018</b>	<b>100</b>	<b>1698.55731</b>

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